IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. II cs INDUSTRIES® international and Pan	PC, Bannockb	urn, Illinois. A	All rights reserved un	nder both	This docume level parts, t	ent is a declara he declaration	tion of th encompa	ne substances asses all lowe	within the r level ma	e manufactur terials for w	er listed ite hich the ma	m. Note: i	if the item is an as r has engineering	sembly with lowe responsibility.
1752-21.1	-21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					ion				
Supplie	r Information														
Company name* Company unique ID					1	Unique ID Authority Response Date*									
onsemi											2023-06-08				
Contact N	lame		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-l	Env-Stewards		Product Envi	Enviro Compliance NA Product-Env-Stewards@onse					vards@onsemi.co	m					
	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Dat	Effective Date Version Manufacturing Sit		ring Site	Weight*		UOM	Unit Type		
		STK554U	U394A-E	3phase inverter HI	C		2023-06-08		,	VN2		1	5700.0	mg	Each
Manufa	cturing Proccess Informat	tion													
	Terminal Plating / Grid Array Material To		erminal Base	rminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperatur		ure Max Time at Peak Tempera		Temperatu	re Numb	per of Reflow Cyc	les	
	Matte Tin (Sn) - annealed	C	CU Alloy	N	JA		0		C	30		second	s 3		
Comments	S														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration 7	Гуре *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% b (Pb), Mercury (Hg), Hexavalent Chromium phthalate (BBP), Dibutyl phthalate (DBP), I	(Cr6+), Polybrominated Biphenyls (PB			
contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided b	ed biphenyls and/or polybrominated diphenyl of an applicable quantity limit, please indicate fies that it gathered the information it provides n. Supplier acknowledges that Company will reverselied on informationprovided by others in a yothers, Supplier agrees that, at a minimum, i and the Supplier enter into a written agreement ource of the Supplier's liability and the Comp	ethers (each a "RoHS restricted substant be below which, if any, RoHS exemption in this form using appropriate method- ely on this certification in determining to completing this form, and that Supplier tssuppliers have provided certifications at with respect to the identified part, the any's remedies for issues that arise reg-	ce") in excess of the appli you believe may apply. If to ensure its accuracy and the compliance of its produce may not have independent regarding their contributions of the	cable quantity limit identified about the part is an assembly with low I that such information is true and cts with European Union membe ly verified such information. How ons to the part, and those certificant agreement, including any warrant.	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not titions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted
Exemption: 7c-I Electrical and electronic co	omponents containing lead in a glass or cera	mic other than dielectric ceramic in	apacitors, e.g. piezoelect	ronic devices, or in a glass or co	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		ccepted" on the Supplier Acceptance	drop-down. This will dis	play the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	astislav Drska	E			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4758.1	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		59.4763	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		234.5743	mg
			В	Nickel (Ni)	7440-02-0		8.0888	mg
			Supplier	Acrylic resins	Proprietary Data		3.3307	mg
			Supplier	Copper (Cu)	7440-50-8		319.7443	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.3791	mg
			Supplier	Aluminum (Al)	7429-90-5		4130.5068	mg
Chip Parts	41.39	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0083	mg
			Supplier	Silver (Ag)	7440-22-4		1.6639	mg
			Supplier	Epoxy resins	129915-35-1		0.4429	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0248	mg
			Supplier	Tin (Sn)	7440-31-5		1.3162	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.0637	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		8.5801	mg
			Supplier	Phenolic resins	Proprietary Data		0.1159	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0083	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		25.0451	mg
			В	Nickel (Ni)	7440-02-0		1.5977	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0911	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0041	mg
			Supplier	Copper (Cu)	7440-50-8		1.428	mg
Die	36.37	mg	Supplier	Silicon (Si)	7440-21-3		36.37	mg
Die Attach	1.8	mg	Supplier	Silver (Ag)	7440-22-4		1.2249	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2702	mg
			Supplier	Tin (Sn)	7440-31-5		0.1919	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0682	mg
			В	Antimony (Sb)	7440-36-0		0.0178	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.027	mg
Heat Sink	1325.05	mg	Supplier	Silver (Ag)	7440-22-4		12.9855	mg
			Supplier	Copper (Cu)	7440-50-8		1312.0646	mg

Lead Frame	849.54	mg	Supplier	Tin (Sn)	7440-31-5	0.5097	mg
			Supplier	Copper (Cu)	7440-50-8	849.0303	mg
Mold Compound-Black	9584.52	mg		Brominated epoxy resin	proprietary data	191.6904	mg
			Supplier	Phenolic Resin	Proprietary Data	575.0712	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data	191.6904	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	287.5356	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	958.452	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	670.9164	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	6709.1636	mg
Plating	11.88	mg	Supplier	Tin (Sn)	7440-31-5	5.94	mg
			В	Nickel (Ni)	7440-02-0	5.94	mg
Solder Ball	44.57	mg	Supplier	Silver (Ag)	7440-22-4	1.3817	mg
			Supplier	Tin (Sn)	7440-31-5	42.8585	mg
			В	Antimony (Sb)	7440-36-0	0.0045	mg
			Supplier	Copper (Cu)	7440-50-8	0.3254	mg
Wire Bond - Al	46.78	mg	Supplier	Aluminum (Al)	7429-90-5	46.78	mg